



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2021-01-08
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	marianna grasso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STIB1560DM2T-LZ	IBZ4*FR67X62	A	3068	2021-01-08
	Amount	UoM	Unit type	ST ECOPACK Grade
	9160	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00723762	

Package Designator	Size	Nbr of instances	Shape	
DIP	38.00,24.00,3.50	26	Through hole	
Comment	SDIP2B-26L			

QueryList : RoHS Directive 2011/65/EU-July 2011 Annex II amended by Delegated Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.16	die - NTC	18

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Cobalt, Gold, Tin, Tungsten,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

Material Composition Declaration :						Mfr Item Name	IBZ4*FR67X62					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	M-011 Other inorganic materials	49.569	mg	supplier	die	Silicon(Si)	7440-21-3		47.288	mg	953982	5164
				supplier	metallisation	Aluminium(Al)	7429-90-5		1.068	mg	21546	117
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.006	mg	121	1
				supplier	metallisation	Gold(Au)	7440-57-5		0.021	mg	424	2
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.084	mg	1695	9
				supplier	metallisation	Silver(Ag)	7440-22-4		0.011	mg	222	1
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.004	mg	81	0
				supplier	metallisation	Tungsten(W)	7440-33-7		0.014	mg	282	2
				supplier	metallisation	Vanadium(V)	7440-62-2		0.003	mg	61	0
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.178	mg	3591	19
				supplier	passivation	Silicon oxide	7631-86-9		0.576	mg	11620	63
				supplier	polymer coating	Durimide	proprietary		0.297	mg	5992	32
				supplier	polymer coating	Polyimide	Proprietary		0.019	mg	383	2
Leadframe	M-004 Copper and its alloys	2853.339	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		2777.587	mg	973452	303230
				supplier	alloy & coating	Iron(Fe)	7439-89-6		65.328	mg	22895	7132
				supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8		3.933	mg	1378	429
				supplier	alloy & coating	Zinc(Zn)	7440-66-6		3.420	mg	1199	373
				supplier	alloy & coating	Silver (Ag)	7440-22-4		3.071	mg	1076	335
Die attach	M-011 Other inorganic materials	2.418	mg	supplier	glue	Silver (Ag)	7440-22-4		1.837	mg	759719	201
				supplier	glue	Oxiranylmethoxy-phenyl-methylene-bisoxiran	13561-08-5		0.290	mg	119934	32
				supplier	glue	Phenol resin	9003-35-4		0.073	mg	30190	8
				supplier	glue	Epoxypropoxy butane polymer	2425-79-8		0.073	mg	30190	8
				supplier	glue	Diglycidyl phenyl allyl ether	EC 417-470-1		0.121	mg	50041	13
				supplier	glue	Polyoxypropylenediamine	9046-10-6		0.024	mg	9926	3
Soft solder	Solder	32.654	mg	supplier	solder	Tin(Sn)	7440-31-5	7a-Lead in high melting temper	31.508	mg	964905	3440
				supplier	solder	Silver(Ag)	7440-22-4		1.143	mg	35003	125
				supplier	solder	flux residue	proprietary		0.003	mg	92	0
Bonding wires	M-003 Aluminum and its alloys	20.095	mg	supplier	wire	Aluminium (Al)	7429-90-5		20.095	mg	1000000	2194
Bonding wires 2	M-008 Precious metals	0.043	mg	supplier	wire	Gold(Au)	7440-57-5		0.043	mg	1000000	5
Bonding wires 3	M-004 Copper and its alloys	1.226	mg	supplier	wire	Copper(Cu)	7440-50-8		1.226	mg	999980	134
	M-008 Precious metals			supplier	wire	Silver(Ag)	7440-22-4		0.000	mg	20	0
Encapsulation	M-011 Other inorganic materials	3476.937	mg	supplier	mold compound	Silica vitreous	60676-86-0		2851.088	mg	820000	311254
				supplier	mold compound	Phenol resin Novolac	26834-02-6		139.078	mg	40000	15183
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		278.155	mg	80000	30366
				supplier	mold compound	Phenol resin	9003-35-4		34.769	mg	10000	3796
				supplier	mold compound	Other	proprietary		163.416	mg	47000	17840
				supplier	mold compound	Carbon black	1333-86-4		10.431	mg	3000	1139
connections coating	Solder	55.236	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		55.236	mg	1000000	6030
DBC	M-010 Ceramics / glass	2668.004	mg	supplier	ceramic	Alumina	1344-28-1		1157.113	mg	433700	126322
				supplier	metallization	Copper(Cu)	7440-50-8		1492.695	mg	559480	162958
				supplier	ceramic	Calcium oxide	1305-78-8		18.196	mg	6820	1986
				supplier	substrate	Manganese tetraoxide	1317-35-7		0.307	mg	640919	34
NTC	M-011 Other inorganic materials	0.479	mg	supplier	metallization	Nickel oxide	1313-99-1		0.077	mg	160752	8
				supplier	metallization	Tricobalt tetraoxide	1308-06-1		0.068	mg	141962	7
				supplier	metallization	Gold(Au)	7440-57-5		0.027	mg	56367	3